



HA8550

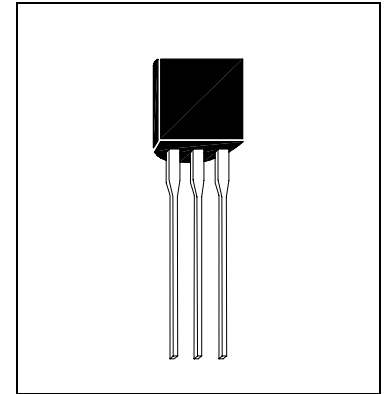
PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HA8550 is designed for use in 2W output amplifier of portable radios in class B push-pull operation.

Features

- High total power dissipation (PT: 2W, TC=25°C)
- High collector current (IC: 1.5A)
- Complementary to HA8050



Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Ta=25°C)..... 1 W
 - Total Power Dissipation (Tc=25°C)..... 2 W
- Maximum Voltages and Currents (Ta=25°C)
 - V_{CB0} Collector to Base Voltage -40 V
 - V_{CEO} Collector to Emitter Voltage..... -25 V
 - V_{EB0} Emitter to Base Voltage..... -6 V
 - I_C Collector Current -1.5 A
 - I_B Base Current -0.5 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
B _V CB0	-40	-	-	V	I _C =-100uA
B _V CEO	-25	-	-	V	I _C =-2mA
B _V EB0	-6	-	-	V	I _E =-100uA
I _C B0	-	-	-100	nA	V _{CB} =-35V
I _E B0	-	-	-100	nA	V _{EB} =-6V
*V _{CE} (sat)	-	-	-0.5	V	I _C =-0.8A, I _B =-80mA
*V _{BE} (sat)	-	-	-1.2	V	I _C =-0.8A, I _B =-80mA
V _{BE} (on)	-	-	-1	V	V _{CE} =-1V, I _C =-10mA
*h _{FE} 1	45	-	-		V _{CE} =-1V, I _C =-5mA
*h _{FE} 2	85	-	500		V _{CE} =-1V, I _C =-100mA
*h _{FE} 3	40	-	-		V _{CE} =-1V, I _C =-800mA
f _T	100	-	-	MHz	V _{CE} =-10V, I _C =-50mA, f=100MHZ

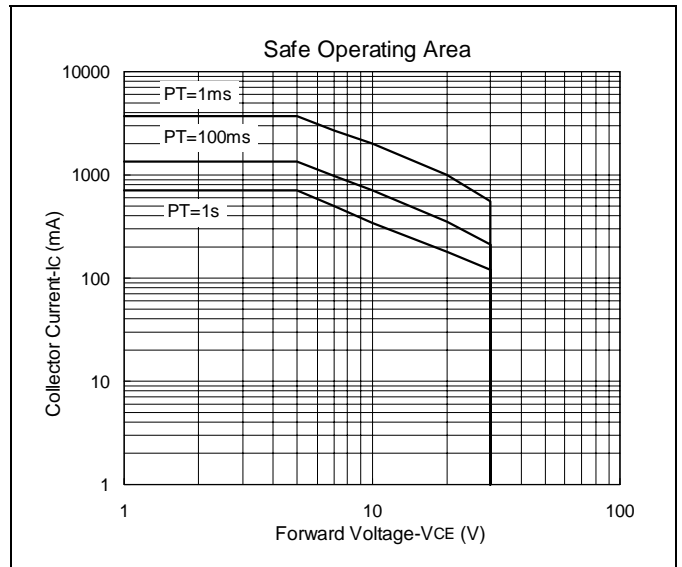
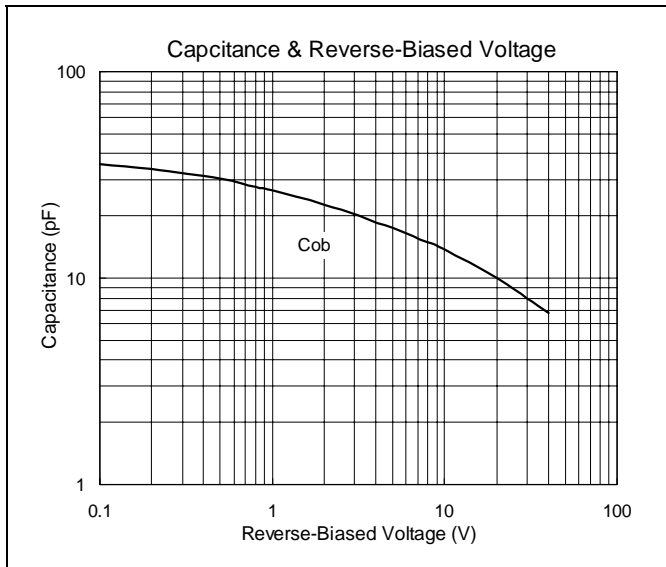
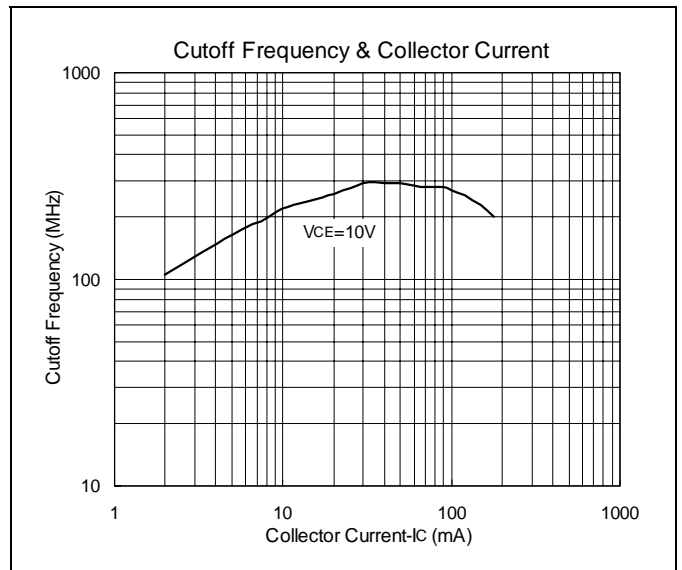
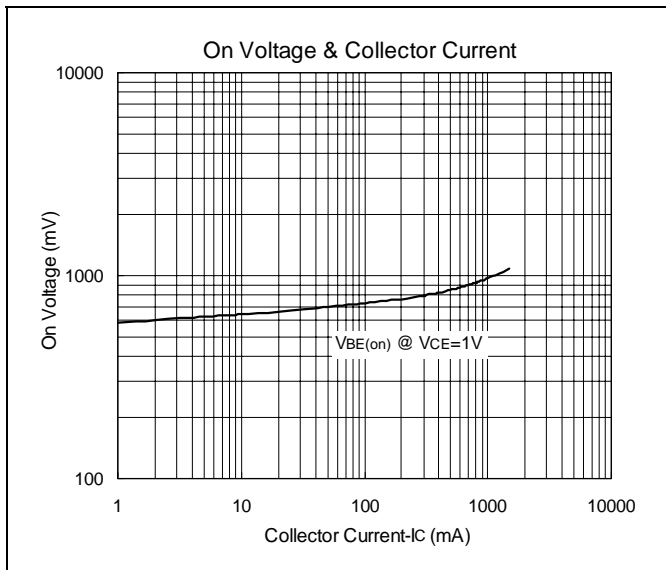
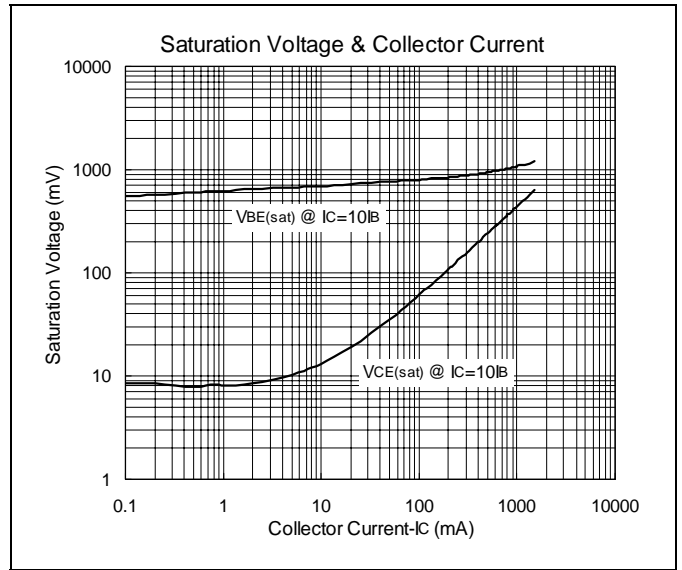
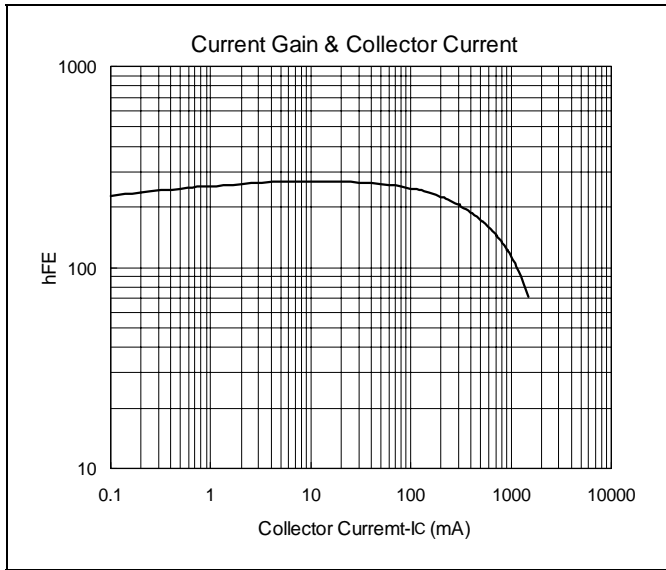
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

Classification on hFE2

Rank	C	D	E
Range	120-200	160-320	250-500

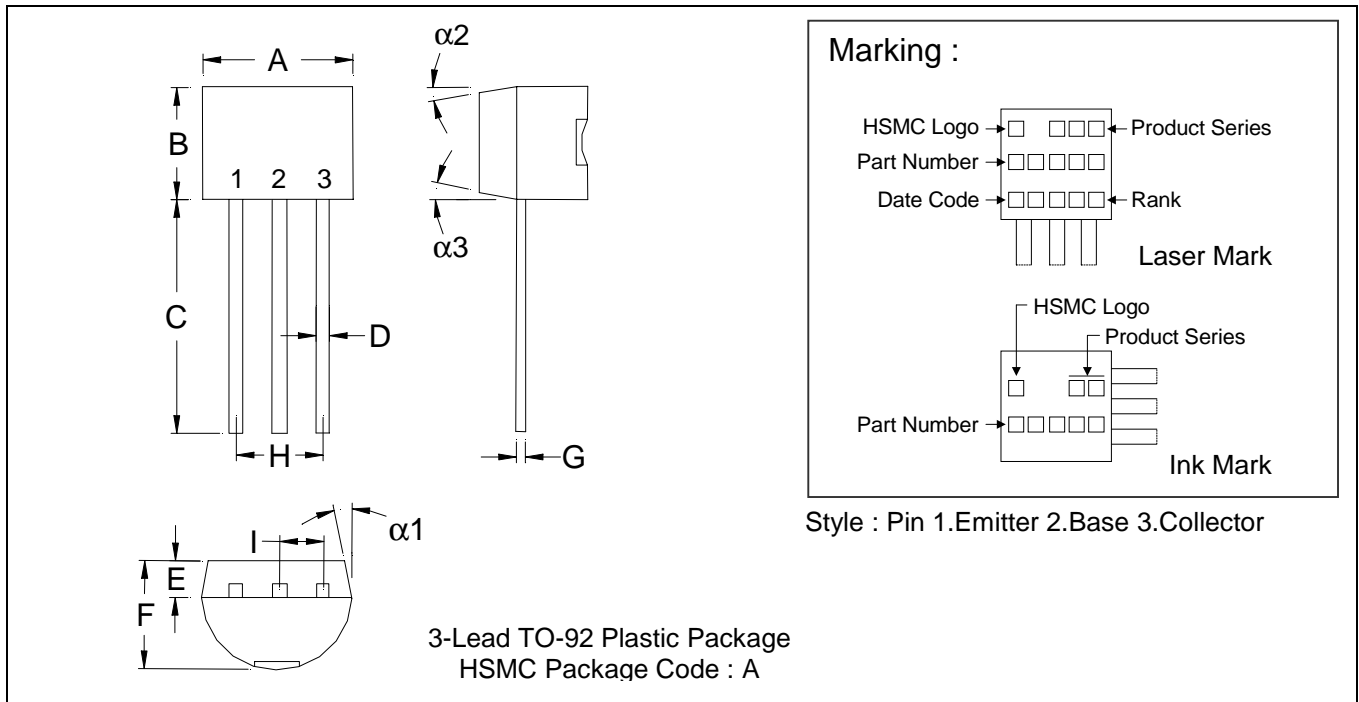


Characteristics Curve





TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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